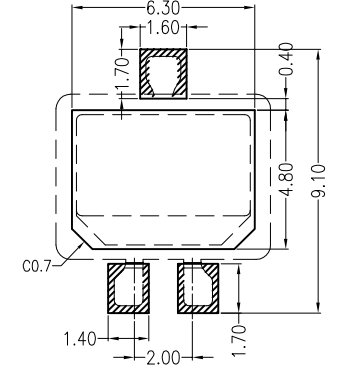
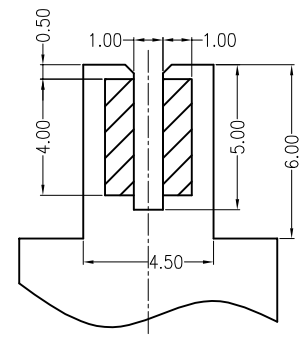
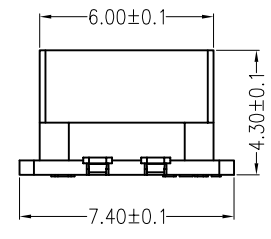
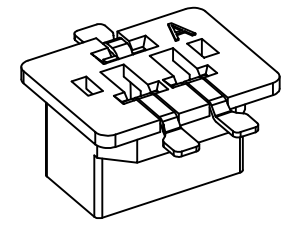
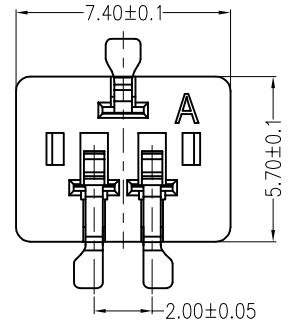
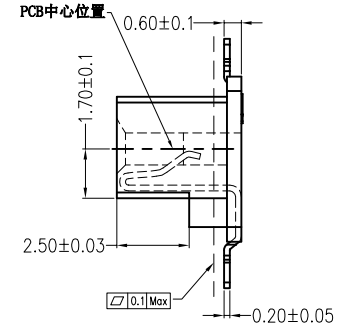
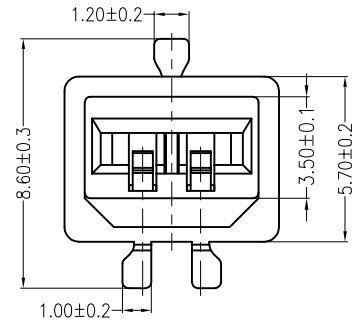


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



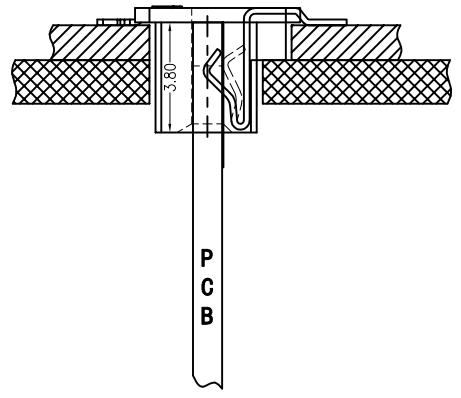
**主要技术参数 Main Specifications**

- 板 厚 (thickness): 1.0mm
- 接触电阻 (Contact resistance):  $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance):  $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐 电压 (Withstand Voltage): 800V AC/minute
- 温度范围 (Temperature Range):  $-40^{\circ}C \sim +120^{\circ}C$

**ORDER INFORMATION:**

**L038-02-F2MB-R**

PART No.		PACKAGING:
No. FOR CIRCUITS:		P=PE
02		R=REEL
PLASTIC MATERIAL:		PLATING:
F2M=LCP (BEIGE)		B=MATTE Sn



**Assembly Layout**

**Mating PCB detail**

**Board Layout**

C	Solder Tab	1 PCS	Brass	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH

<b>广东科斯达电子科技有限公司</b> GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.		TITLE: -	
		2.0mmPITCH 180*WAFER SMT TYPE	
X.±0.5	X.±5'	USE:	PART NO.:
.X±0.3	.X±2'	CUSTOMER	L038-02-F2MB-R
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:
--	--	CHKD: 田峰	JKUN/GCCP-0063
UNITS: mm		DR: 周秀龙	SCALE: 1 : 1
			SHEET: 1 / 1